# Reduced Geometry Probing

#### Southwest Test Conference

May 31-June 3, 1998 By: Mike Chrastecky, Central Sales Mgr. WWLABS@aol.com



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# Goal

To determine the performance window of reliable and consistent electro-mechanical performance for small pad probing.





# Why?





Thermo compression ball bonding at 70um pitch with 65um bond pad size. Ultrasonic wedge bonding at 60um pitch with 56X44um bond pad size.



## 33% shrink



![](_page_3_Picture_2.jpeg)

## 1.5mil tip @ 3mils OD

![](_page_4_Picture_1.jpeg)

#### 100 um

![](_page_4_Picture_3.jpeg)

## 33% shrink

![](_page_5_Picture_1.jpeg)

#### 100 um

![](_page_5_Picture_3.jpeg)

1.5 mil tip diameter with 1 of scrub utilizes 2.5 mils of y axis dimension with 17um passivation to tip spacing.

![](_page_6_Picture_1.jpeg)

1.0 mil tip diameter with 1 mil scrub utilizes 2 mils of y axis dimension with 7um passivation to tip spacing.

![](_page_6_Picture_3.jpeg)

65 um

NENTWORTH

100 um

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# Here's the problem...

Conventional alignment and planarity specifications coupled with today's manual alignment capabilities are currently limited to .0002 to .00025 from true position.

![](_page_7_Picture_2.jpeg)

![](_page_7_Picture_3.jpeg)

# Here's what we tried...

![](_page_8_Picture_1.jpeg)

 1. Design in directional control of probe to pad scrub.

![](_page_8_Picture_3.jpeg)

### Straight Approach Design Model

![](_page_9_Figure_1.jpeg)

![](_page_9_Picture_2.jpeg)

#### Stack Design Model

![](_page_10_Picture_1.jpeg)

![](_page_10_Picture_2.jpeg)

#### Stack Design Model

![](_page_11_Picture_1.jpeg)

![](_page_11_Picture_2.jpeg)

# then...

![](_page_12_Picture_1.jpeg)

 1. Overdrive was reduced to shorten scrub.

![](_page_12_Picture_3.jpeg)

## 3 vs. 1.5mils OD

![](_page_13_Figure_1.jpeg)

![](_page_13_Picture_2.jpeg)

65 um

65 um

![](_page_13_Picture_5.jpeg)

# and...

![](_page_14_Figure_1.jpeg)

- Increase gram force by shortening beam length to compensate for loss of force due to a 1/2X OD.
- 2X, 4gms/mil vs. standard of 2gms/mil overdrive.

![](_page_14_Picture_4.jpeg)

# finally...

![](_page_15_Picture_1.jpeg)

P&A tolerance specifications were tightened.

![](_page_15_Picture_3.jpeg)

# We had problems...

- Auto Probe Align
- Contamination
- Continuity Degradation

![](_page_16_Picture_4.jpeg)

![](_page_16_Picture_5.jpeg)

## Auto Prober Align

![](_page_17_Figure_1.jpeg)

![](_page_17_Picture_2.jpeg)

## Contamination

Aluminum flaking contamination due to the shaving of bond pad resulting from high gram force.

![](_page_18_Picture_2.jpeg)

# Continuity

Resistance problems due to premature build up of nonconductive pad oxides due to excessive force and lack of scrub.

![](_page_19_Picture_2.jpeg)

# Where do we go now?

![](_page_20_Picture_1.jpeg)

New Designs

 Electro-Mechanical Characterization

Experimental Matrix

![](_page_20_Picture_5.jpeg)

## **Real Data Collection**

#### Reduced Geometry Probing Experimental Matrix.

Card #

Pad Size:

#### Mechanics

Wire	Beam	Probe	Beam	Gram	Тір	Тір	Tip
Diameter	Length	Taper	Angle	Force	Angle	Length	Da.
mils	mils	mils	deg	Per mil OD	deg	mils	mils
5	93	60	12 deg	2	103 deg	14	0.8

Performance	1 mil	1.5 mils	2 mils	2.5 mils
Scrub Length (capture)	?	?	?	?
Scrub Length (pad)	?	?	?	?
Resistance	?	?	?	?

![](_page_21_Picture_7.jpeg)

# Goal

To determine the performance window of reliable and consistent electro-mechanical performance for small pad probing.

![](_page_22_Picture_2.jpeg)

![](_page_22_Picture_3.jpeg)

# Thanks

## Pete Dodd, Advanced Micro Devices

## Matt Lauderdale, Motorola

## Rey Rincon, Texas Instruments

![](_page_23_Picture_4.jpeg)

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![](_page_24_Picture_3.jpeg)

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